

the same resin material and a conductor circuit built on each of said resin insulating layers,

wherein said resin insulating layers comprise thermosetting polyolefin resin, or a mixed resin of a thermosetting resin containing at least one member selected from among thermosetting polyolefin resin, epoxy resin, polyimide resin, phenolic resin and bis (maleimide) triazine resin, and a thermoplastic resin, and

each of said conductor circuits are formed on the surfaces of said resin insulating layers by way of a metal layer composed of at least one metal selected from among metals (exclusive of Cu) of the 4th through 7th periods in Group 4A through Group 1B of the long-form periodic table of the elements, Al and Sn.

26 (amended). The multilayer printed circuit board according to Claim 25 wherein each of said metal layers is a layer containing at least one metal selected from among Al, Fe, W, Mo, Sn, Ni, Co, Cr, Ti and noble metals.

27 (amended). The multilayer printed circuit board according to Claim 25 wherein each of said resin insulating layers has a flat and level surface.

29 (amended). The multilayer printed circuit board according to Claim 25 wherein each of said resin insulating layers has a surface obtained by plasma treatment or corona discharge treatment.

30 (amended). The multilayer printed circuit board according to Claim 25 wherein each of said conductor circuits has a metal layer composed of at least one metal selected from among metals (exclusive of Cu) of the 4th through 7th periods in

Group 4A through Group 1B of the long-form periodic table of the elements, Al and Sn on its surface and said metal layer on the surface of said conductor circuits has an interlayer resin insulating layer or a solder resist layer built thereon.

31 (amended). The multilayer printed circuit board according to Claim 25 wherein each of said metal layers built on the surface of said resin insulating layers has a Cu layer formed on its surface and said Cu layer has a conductor circuit constructed thereon.

32 (amended). The multilayer printed circuit board according to Claim 25 wherein the thickness of each of said metal layers is 0.01 to 0.2 μm .

Please add the following new claim:

64. (New) The multilayer printed circuit board according to Claim 25 wherein each of the metal layers are formed by plating, PVD or CVD.

65 (New). The multilayer printed circuit board according to Claim 25 wherein said polyolefin resin has dielectric constant value not more than 3 and dielectric loss tangent value not more than 0.05.

66 (New). The multilayer printed circuit board according to Claim 25 wherein said resin insulating layer has a flat and level surface with an average roughness value of RA being not more than 1 μm .